Industrial Applications of Electron Accelerators

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Presentation Outline

Introduction

Basic Concepts of Radiation Processing

Applications of Radiation Processing

Physical Aspects of Radiation Processing

Industrial Electron Accelerators

Conclusion

Definition of Radiation Processing

The treatment of products and materials with radiation or ionizing energy to change their physical, chemical or biological characteristics, to increase their usefulness and value or to reduce their impact on the environment.

Ionizing Energy Sources

Electrons from Particle Accelerators. X-Rays from Accelerated Electrons. Gamma Rays from Radioactive Nuclides.

In absorbing materials, electrons, X-rays and gamma rays transfer their energies by ejecting atomic electrons, which can then ionize other atoms. These radiations produce similar effects.

Ionizing Energy Sources

Electrons from Particle Accelerators. X-Rays from Accelerated Electrons. Gamma Rays from Radioactive Nuclides.

The choice of a radiation source depends on the practical aspects of the treatment process, such as absorbed dose, material thickness, processing rate, capital and operating costs.

Radiation processing was introduced fifty years ago. Many practical applications have been discovered. The most important commercial applications are:

Modification of plastic and rubber materials. Sterilization of medical devices and consumer items. Pasteurization and preservation of foods. Reduction of environmental pollution.

Absorbed Dose Definition

Temperature Rise vs Absorbed Dose

Absorbed Dose Requirements

Absorbed Dose vs M_W and G Value

Absorbed Dose Definition

Absorbed dose is proportional to the ionizing energy delivered per unit mass of material.

Dose is the most important specification for any irradiation process.

The quantitative effects of the process are related to the absorbed dose.

Absorbed Dose Definition

Energy Absorbed Per Unit Mass International Unit Is The Gray

1 Gy = 1 J/kg
1 Gy = 1 W s/kg
1 kGy = 1 kJ/kg
1 kGy = 1 kW s/kg
1 kGy =
$$(1/3600)$$
 kW h/kg

Absorbed Dose Definition

Energy Absorbed Per Unit Mass Obsolete Unit Is The Rad

> 1 Gy = 100 rad 10 Gy = 1 krad 100 Gy = 10 krad 1 kGy = 100 krad 10 kGy = 1 Mrad100 kGy = 10 Mrad

Temperature Rise vs Absorbed Dose

Temperature rise is proportional to the thermal energy absorbed per unit mass of heated material.

Also, temperature rise is proportional to the absorbed dose in irradiated material (in same units).

Calorimetry is the primary method for measuring absorbed dose and calibrating secondary dosimeters.

Temperature Rise vs Absorbed Dose

 $\Delta T = H / c$

 $\Delta T = D / c$

∆T = Temperature Rise in °C
H = Heat per Unit Mass in J/g
c = Heat Capacity in J/g °C
D = Absorbed Dose in kGy

Basic Concepts of Radiation Processing		
Examples – Temp. Rise per kGy		
Material	Thermal Cap.	Temp. Rise
Water	4.19	0.24
Polyethylene	2.30	0.43
Teflon	1.05	0.95
Aluminum	0.90	1.11
Iron	0.44	2.27
Copper	0.38	2.63

Basic Concepts of Radiation Processing Temperature Rise for EB Processing

Industrial EB processes need less energy than most thermal treatment processes.

Absorbed dose requirements for various industrial processes cover a very wide range from 0.1 kGy to 1000 kGy.

Most of these processes need less than 100 kGy, many need less than 10 kGy, and some need less than 1 kGy.

Absorbed Dose Requirements

Sprout Inhibiting Insect Disinfesting Parasite Control Delay of Ripening Fungi Control Bacteria Control

- 0.1 0.2 kGy 0.3 - 0.5 kGy 0.3 - 0.5 kGy 0.5 - 1.0 kGy1.5 - 3.0 kGy
- $1.5 3.0 \,\mathrm{kGy}$

Absorbed Dose Requirements

Sterilizing Polymerizing Grafting Crosslinking Degrading Gemstone Coloring

15 - 30 kGy 25 - 50 kGy 25 - 50 kGy 50 - 150 kGy 500 - 1500 kGy >> 1500 kGy

Basic Concepts of Radiation Processing Absorbed Dose vs Molecular Weight M_w and G Value $D = N_{A} (100 / G) e / M_{W}$ joules / gram $D = 9.65 \times 10^6 / (G M_w) kGy$ $N_A = 6.022 \times 10^{23}$ molecules / mole $e = 1.602 \times 10^{-19}$ joules / electron volt G = number of chemical reactions / 100 eV

Absorbed Dose vs $\ensuremath{M_W}\xspace$ and G Value

High molecular weight means acceptably low dose.

If $M_W = 100,000$ and G = 1, then D = 100 kGy.

Low molecular weight means excessively high dose.

If
$$M_W = 100$$
 and $G = 3$, then $D = 32,000$ kGy.

Basic Concepts of Radiation Processing Absorbed Dose vs M_W and G Value

Polymeric materials with high molecular weights are good candidates for radiation processing.

Inorganic compounds with low molecular weights are poor candidates for radiation processing.

Dilute solutions are exceptions. Ionizing a small fraction of the solvent will affect most of the solute.

Modifying Polymeric Materials Curing Monomers and Oligomers Grafting Monomers onto Polymers Crosslinking Polymers Degrading Polymers

Biological Applications Sterilizing Medical Products Disinfecting Consumer Products Pasteurizing and Preserving Foods

Environmental Applications Reducing Acid Rain Treating Waste Materials

Solid State Applications Modifying Semiconductors Coloring Gemstones

Modifying polymeric materials

Curing

Grafting

Crosslinking

Degrading

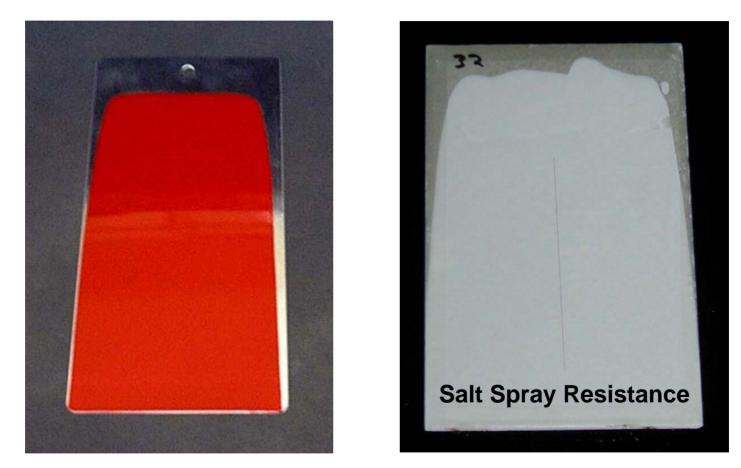
Curing Solvent-Free Coatings, Inks and Adhesives

Oligomers Acrylated epoxies Acrylated polyethers Acrylated urethane polyesters Multifunctional monomers Trimethylolpropane triacrylate

Dose = 10 to 30 kGy

Low-Energy EB Curing of Colored Coatings





Laboratory Test Panels



Curing Composite Materials for Spacecraft and Missiles

Oligomers Modified epoxies with special properties

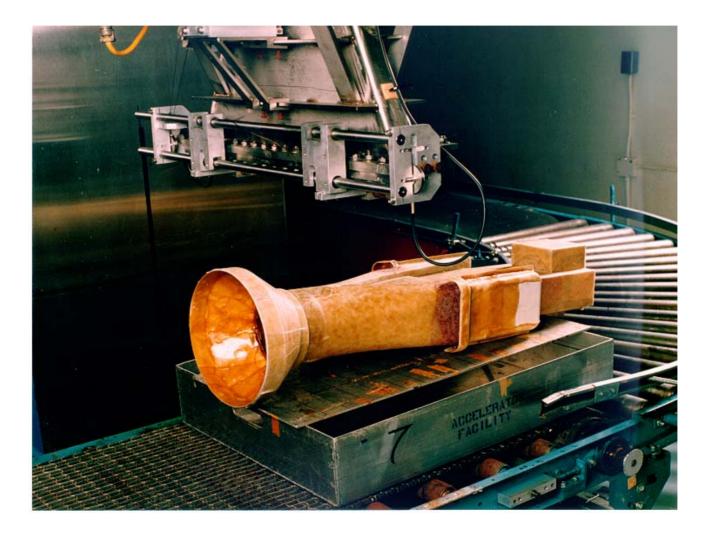
Carbon fiber reinforcement

Dose = 150 to 250 kGy

EB Curing of Carbon Fiber Composite Tank



EB Curing of Composite Missile Component



Materials Suitable for Grafting

A variety polymeric materials Polyethylene, Polypropylene Polyvinyl Chloride, Fluoropolymers Cellulose, Wool

A variety of hydrophilic monomers

Dose = 10 kGy

Property Improvements by Grafting

Addition of hydrophilic surfaces on hydrophobic polymers to make permselective membranes.

Fuel cell and battery separator films.

Improvement of surface adhesion properties.

Biocompatible materials for medical applications.

Typical Materials for Crosslinking

Polyethylene Polyvinylchloride Polyvinylidene fluoride Ethylene-propylene rubber Ethylene vinylacetate Polyacrylates

Dose = 50 to 200 kGy

G value: yield in number of molecules per 100 eV $G_x = cross-linking, G_s = chain scission$ G values at room temperature in the absence of O₂

Polymer G_x G_s Polymer G_x G_s Nat. Rubber1.3-1.50.1-0.2PTFE0.1-0.33.0-5.0Polyethylene0.3-1.30.4-0.5Butyl Rubber<0.5</td>2.9-3.7Polypropylene0.3-1.10.3-1.8PMMA<0.5</td>1.1-1.7

Products Improved by Crosslinking

Plastic Products in Finished Form Heat Shrinkable Tubing and Film Electrical Wire and Cable Jackets Tires for Automobiles and Trucks Plastic Foam Padding for Automobiles Bulk Plastic Materials Hydrogel Materials

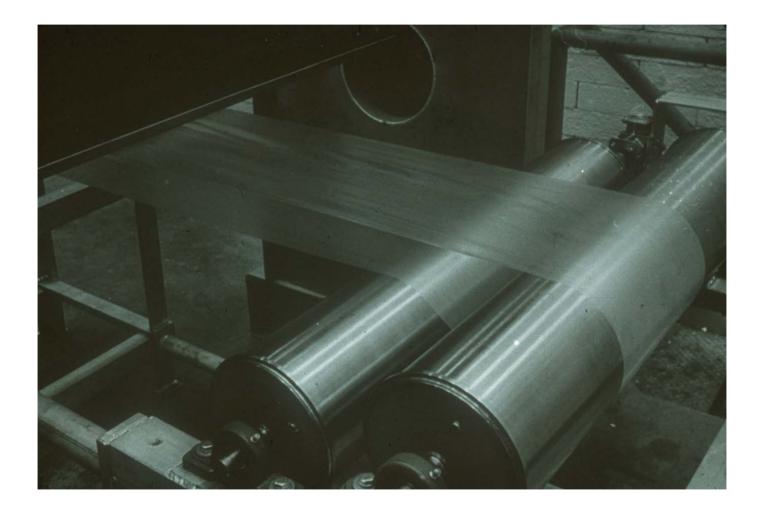
Crosslinking Formed Plastic Products



Crosslinking Heat-Shrinkable Tubing Plastic Memory Effect



Irradiating Heat-Shrinkable Plastic Film



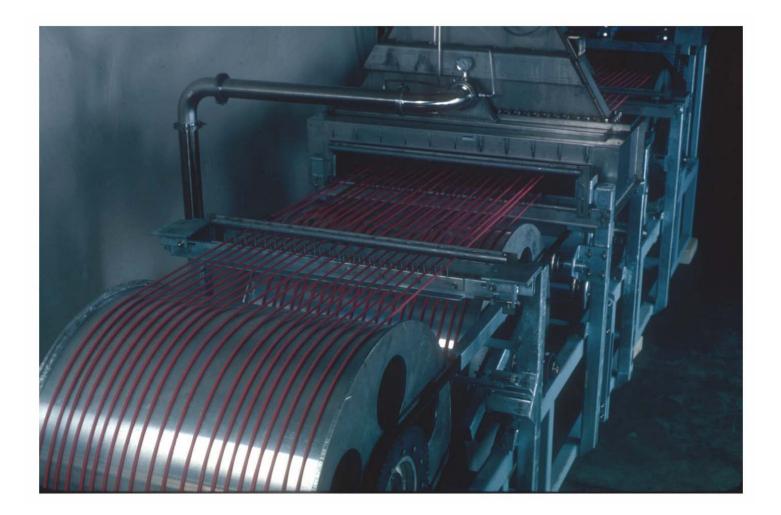
Crosslinking Electrical Wire Insulation Improved Flame Retardancy



Crosslinking Jackets on Multi-conductor Cables



Wire and Tubing Irradiation Method



Precuring Automobile Tire Components Improved Dimensional Stability



Irradiating Plastic Foam Cushions for Cars



Applications of Radiation Processing

Degrading polymeric materials

Polytetrafluoroethylene – for powders

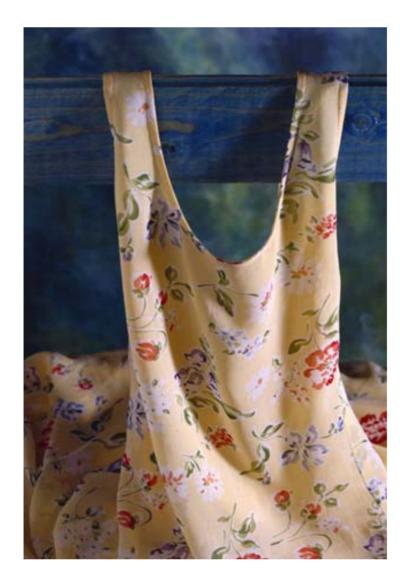
Polypropylene – to improve formability

Cellulose – to produce viscose for rayon

Degrading Scrap Polytetrafluoroethylene



Cellulose Degradation for Viscose and Rayon



Applications of Radiation Processing

Biological Applications

Sterilizing Medical Products

Disinfecting Consumer Products

Pasteurizing and Preserving Foods

Sterilizing Disposable Medical Products



Disinfecting Cosmetic Products



Disinfesting Fresh Fruits and Vegetables



Pasteurizing Uncooked Meats



Pasteurizing Natural Spices



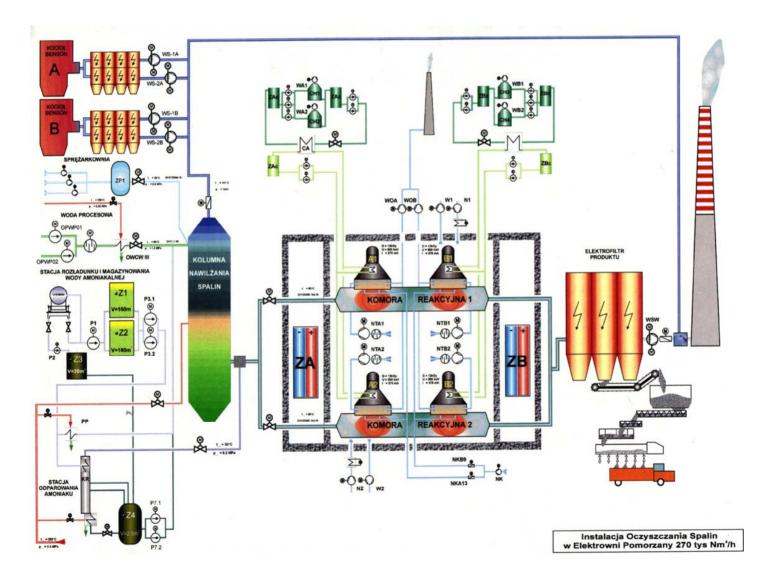
Applications of Radiation Processing

Environmental Applications

Reducing Acid Rain – by extracting sulfur and nitrogen oxides from smoke

Treating Waste Materials – by decomposing toxic substances from wastewater

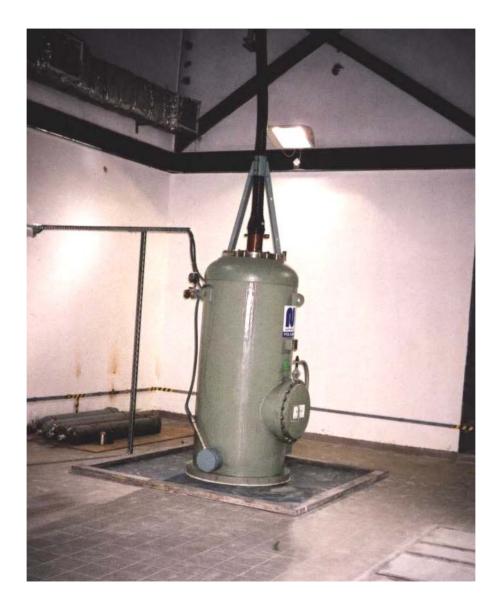
Pomorzany Flue Gas EB Process Flow Diagram



Pomorzany Flue Gas EB Irradiation Vessel



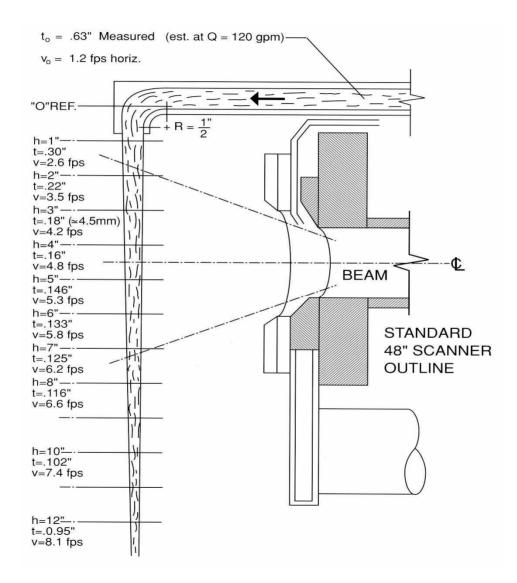
NHV DC Electron Accelerator 700 keV – 260 kW



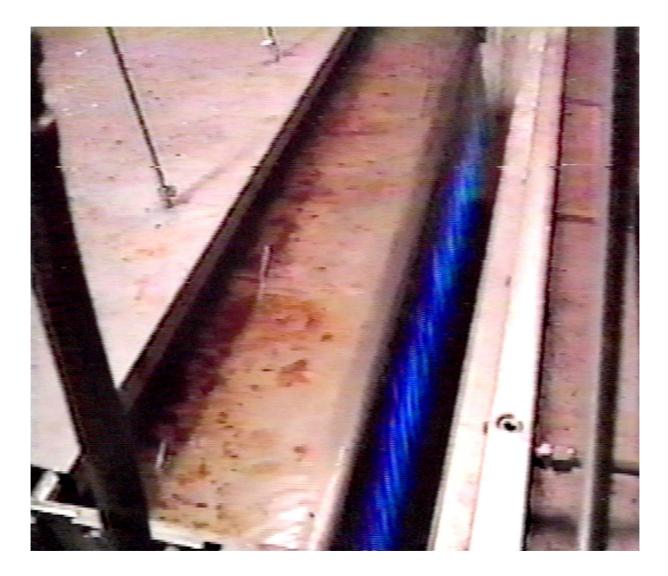
Wastewater Treatment Plant



Miami Dade County EB Wastewater Treatment



Miami Dade County EB Wastewater Treatment



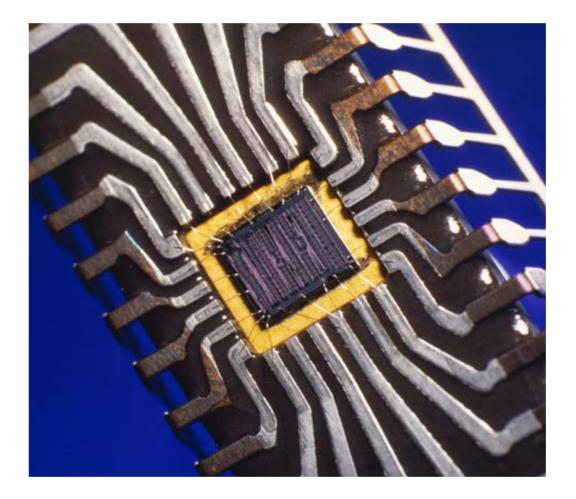
Applications of Radiation Processing

Solid State Applications

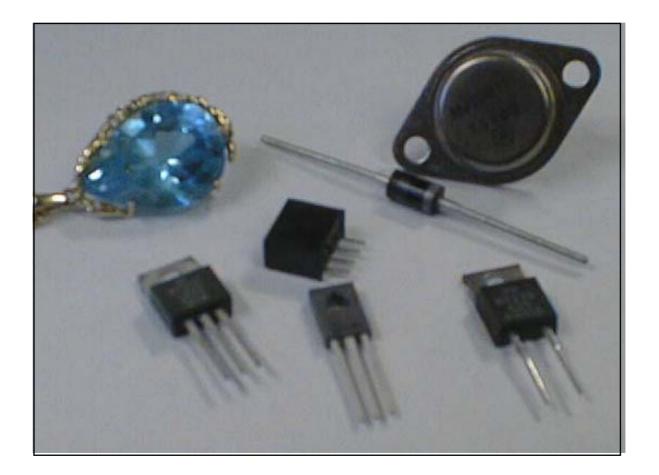
Modifying Semiconductors

Coloring Gemstones

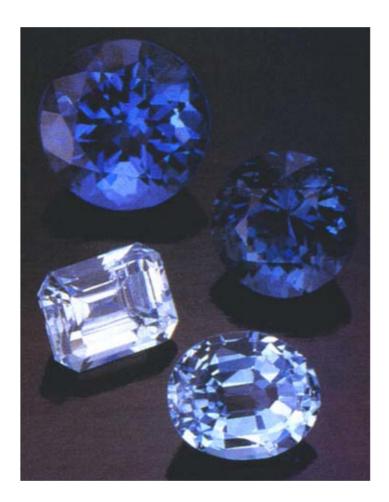
Modifying Semiconductors



Modifying Semiconductors



Coloring Gemstones



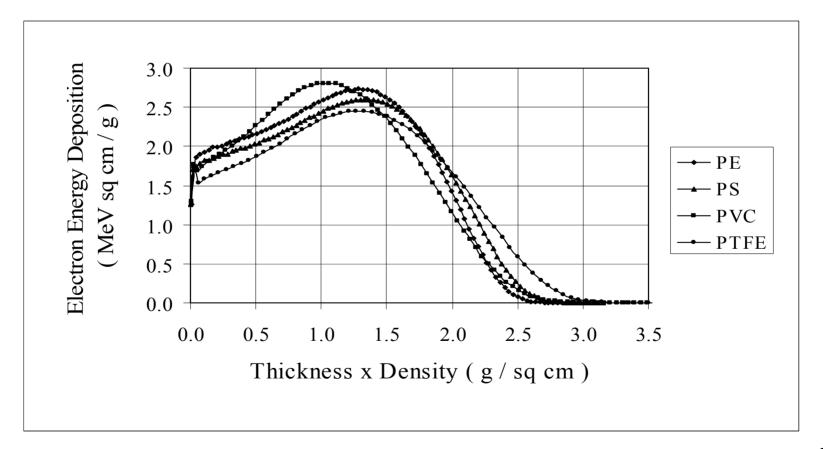
Material Penetration vs Electron Energy

Mass Throughput Rate vs Electron Beam Power

Area Throughput Rate vs Electron Beam Current

X-Ray Processing Characteristics

Physical Aspects of Radiation Processing Penetration vs Electron Energy Polymer Comparisons – 5 MeV



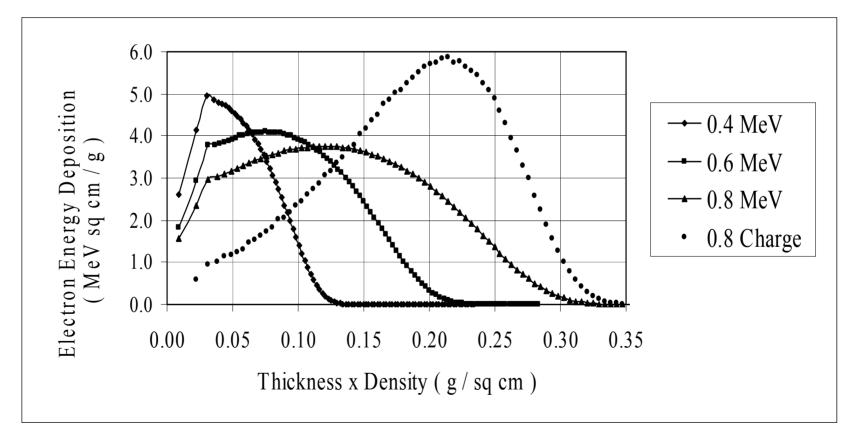
Physical Aspects of Radiation Processing Penetration vs Electron Energy Polymer Comparisons

Hydrogen has more atomic electrons per unit mass than any other element.

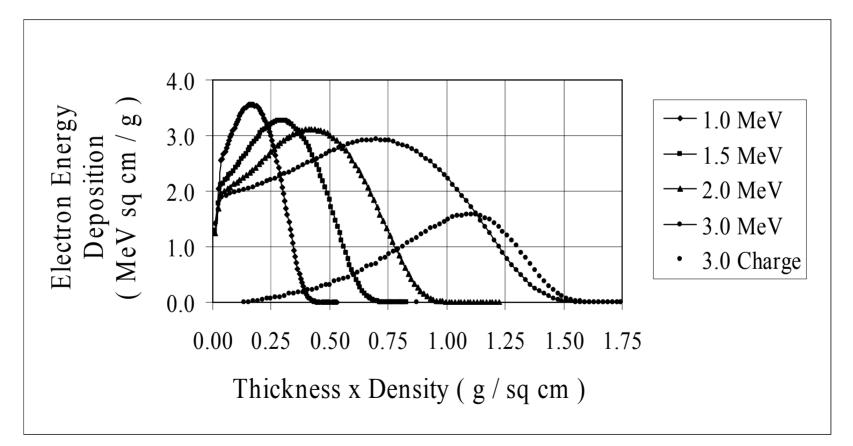
Polymers with more hydrogen have higher energy depositions per incident electron.

Polymers with more hydrogen have lower electron ranges for the same incident electron energy.

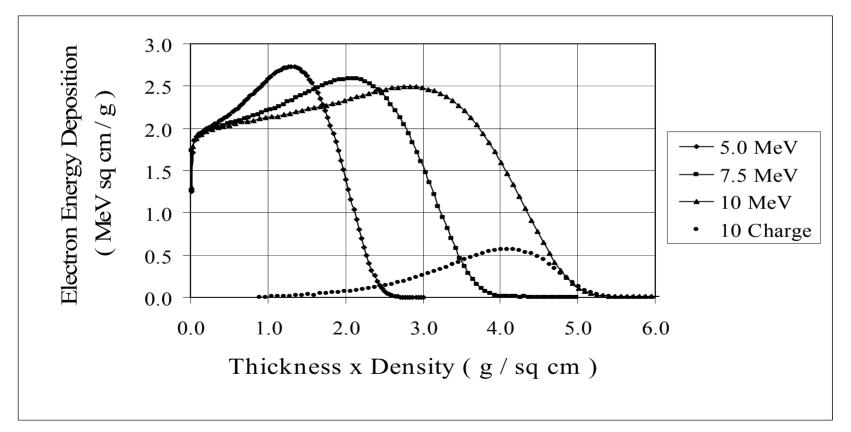
Physical Aspects of Radiation Processing Penetration vs Electron Energy Polyethylene



Physical Aspects of Radiation Processing Penetration vs Electron Energy Polyethylene



Physical Aspects of Radiation Processing Penetration vs Electron Energy Polyethylene



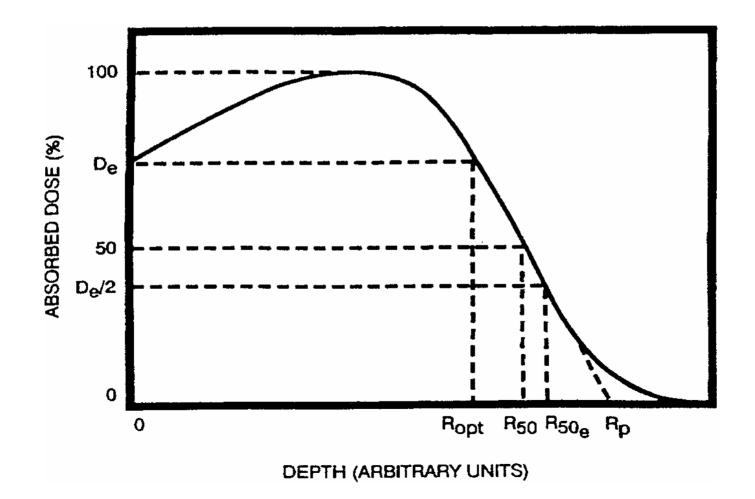
Penetration vs Electron Energy Electrostatic Charge Deposition

Electrostatic charges are deposited by incident electrons which come to rest in thick materials.

The charge depositions are concentrated near the Ends of the electron ranges.

The charge density decreases and the total energy deposition increases as the incident electron energy increases.

Electron Range Definitions



Electron Range Definitions

R(opt) – Exit Dose Equals Entrance Dose

R(50) – Exit Dose Equals Half Maximum Dose

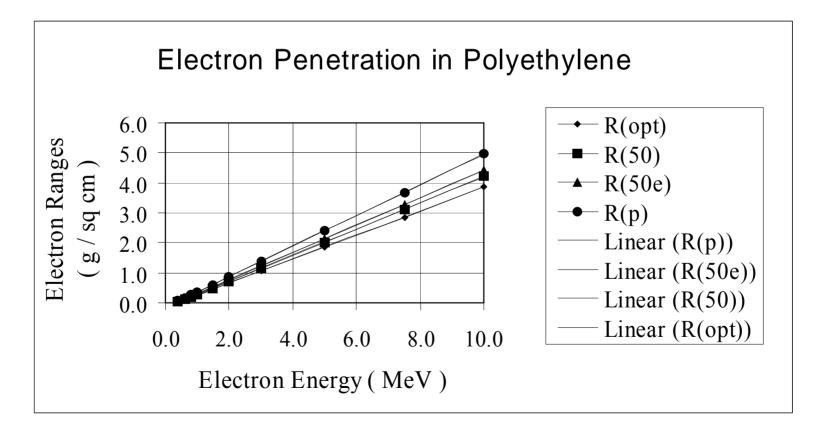
R(50e) – Exit Dose Equals Half Entrance Dose

R(p) – Tangent Line Extends to Zero Dose

Physical Aspects of Radiation Processing Electron Range Values

MeV	R(opt)	R(50)	R(50e)	R(p)
0.4	0.000	0.054	0.054	0.083
0.6	0.075	0.126	0.129	0.169
0.8	0.161	0.202	0.214	0.262
1.0	0.243	0.282	0.302	0.358
1.5	0.449	0.486	0.529	0.610
2.0	0.652	0.699	0.754	0.861
3.0	1.054	1.128	1.209	1.373
5.0	1.859	2.000	2.131	2.405
7.5	2.854	3.134	3.284	3.682
10.0	3.884	4.204	4.429	4.955

Electron Range Graphs



Linear Range vs Energy Equations

R(opt) = 0.404 E - 0.161

R(50) = 0.435 E - 0.152

R(50e) = 0.458 E - 0.152

R(p) = 0.510 E - 0.145

Ranges in Other Materials

Electron ranges in other materials can be estimated by multiplying the polyethylene range with the ratio of their CSDA ranges.

 $R(material) = R(polyethylene) \times CSDA(m) / CSDA(pe)$

CSDA ranges for many materials with a wide range of electron energies can be obtained from ICRU Report 37.

Absorbed Dose vs Electron Beam Power

1 kGy = 1 kJ/kg

D(ave) = F(p) P T / M

D(ave) = F(p) P / (M / T)

D(ave) = average dose in kGy P = emitted power in kW T = treatment time in s M = mass in kg

Mass Throughput Rate vs Electron Beam Power

M / T = F(p) P / D(ave)

$$F(p) = F(e) F(i)$$

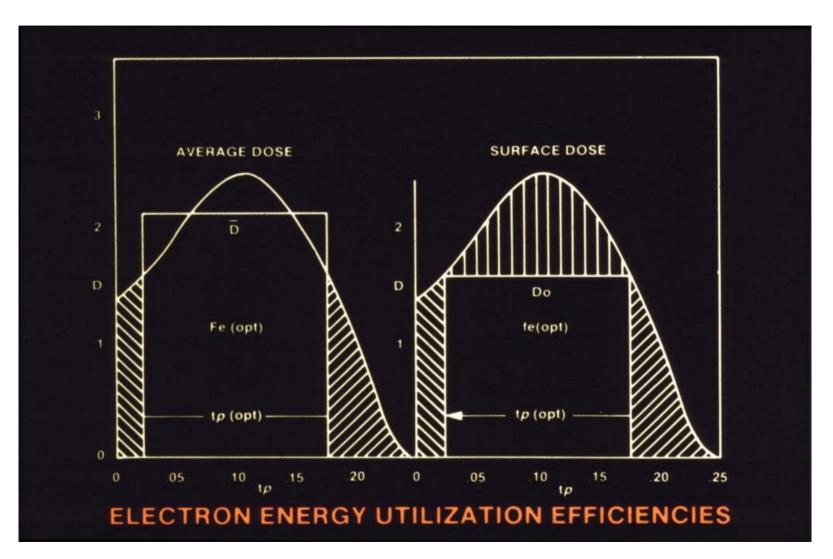
F(p) = fraction of emitted power absorbed F(e) = fraction of incident power absorbed F(i) = fraction of emitted current intercepted

Mass Throughput Rate vs Electron Beam Power

M / T = f(p) P / D(o)

$$f(p) = f(e) F(i)$$

D(o) = surface dose in kGy f(p) = surface dose value of F(p) f(e) = surface dose value of F(e)



Processing Parameters vs Incident Energy

MeV	D(e)	K(o)	f(e)	F(e)
0.4	4.963	0.496	0.000	0.000
0.6	3.795	0.380	0.474	0.496
0.8	2.982	0.298	0.599	0.695
1.0	2.550	0.255	0.619	0.777
1.5	2.118	0.212	0.634	0.850
2.0	1.966	0.197	0.641	0.862
3.0	1.887	0.189	0.663	0.867
5.0	1.860	0.186	0.692	0.875
7.5	1.860	0.186	0.708	0.873
10.0	1.878	0.188	0.730	0.867

Example – Mass Throughput Rate

E = 1.0 MeV P = 100 kW F(i) = 0.80 f(e) = 0.619D(o) = 100 kGy

 $M / T = 0.619 \ge 0.80 \ge 100 / 100$

M / T = 0.495 kg/s or 1783 kg/h

Absorbed Dose vs Electron Beam Current

D (kGy) = P (kW) T (s) / M (kg)

P(kW) = E(MeV) I(mA)

 $E (MeV) = D(e) (MeV cm^2/g) Z (g/cm^2)$

D(e) = energy deposition per electron Z = thickness x density (g/cm²)Z = mass / area (g/cm²)

Absorbed Dose vs Electron Beam Current

D (kGy) = E (MeV) I (mA) T (s) / M (kg)

D(kGy) = D(e) Z I(mA) T(s) / M(kg)

D (kGy) = D(e) Z I (mA) T (s) / Z A (cm²) 10⁻³

 $D (kGy) = D(e) I (mA) T (s) / 10 A (m^2)$

Absorbed Dose vs Electron Beam Current

D(z) = K(z) F(i) I T / A

D(z) = dose at the depth z in kGy $K(z) = D(e, z) / 10 \text{ in kGy m}^2/mA \text{ s}$ K(z) = Area Processing Coefficient - evaluatedat the depth where the dose is specified F(i) = fraction of emitted beam current intercepted I = emitted beam current in mAT = treatment time in s $A = product area in m^2$

Area Throughput Rate vs Electron Beam Current

$$A / T = K(z) F(i) I / D(z)$$

A / T = area throughput rate in m²/s K = D(e) / 10 in kGy m²/mA s K = Area Processing Coefficient F(i) = fraction of beam current intercepted F(i) = product area / irradiated area I = emitted beam current in mA D(z) = dose in kGy where K(z) is evaluated

Processing Parameters vs Incident Energy

MeV	D(e)	K(o)	f(e)	F(e)
0.4	4.963	0.496	0.000	0.000
0.6	3.795	0.380	0.474	0.496
0.8	2.982	0.298	0.599	0.695
1.0	2.550	0.255	0.619	0.777
1.5	2.118	0.212	0.634	0.850
2.0	1.966	0.197	0.641	0.862
3.0	1.887	0.189	0.663	0.867
5.0	1.860	0.186	0.692	0.875
7.5	1.860	0.186	0.708	0.873
10.0	1.878	0.188	0.730	0.867

Example – Area Throughput Rate

E = 1.0 MeV I = 100 mA F(i) = 0.80 K(o) = 0.255D(o) = 100 kGy

A / T = $0.255 \ge 0.80 \ge 100 / 100$

A / T = $0.204 \text{ m}^2/\text{s}$ or 734 m²/h

Example – Mass Throughput from Area Throughput

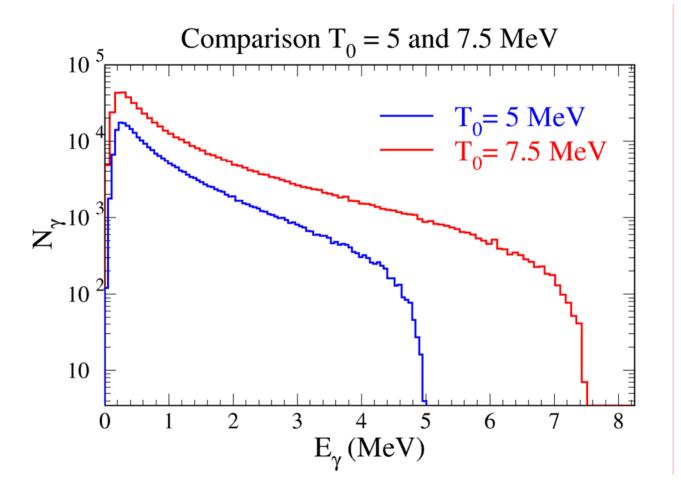
E = 1.0 MeVI = 100 mA F(i) = 0.80 R(opt) = 0.243 g/cm² or 2.43 kg/m² A / T = 734 m²/h

 $M / T = (A / T) \times R(opt)$

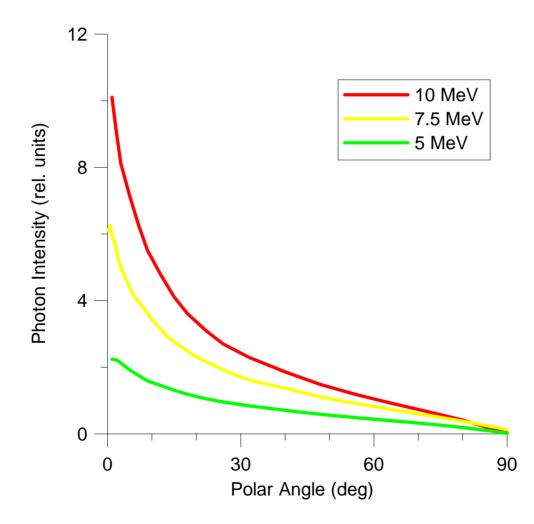
M / T = 734 x 2.43 = 1785 kg/h

Physical Aspects of Radiation Processing X-Ray Processing Characteristics X-Ray Energy and Angular Distributions X-Ray Broad Beam Penetration in Water X-Ray Utilization vs Product Thickness X-Ray Emission Efficiency vs Electron Energy PalletronTM Rotational X-Ray Processing

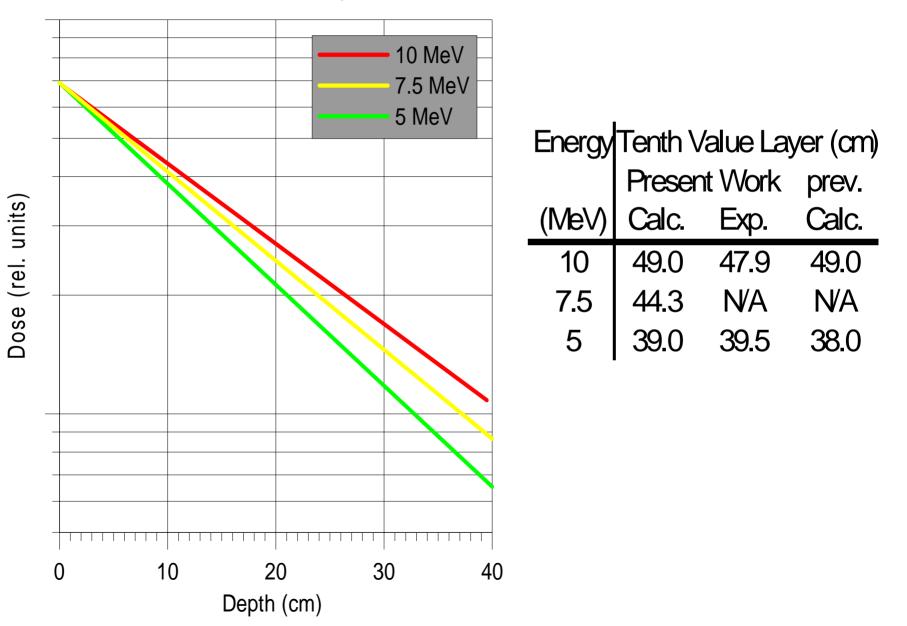
X-Ray Photon Energy Spectrum



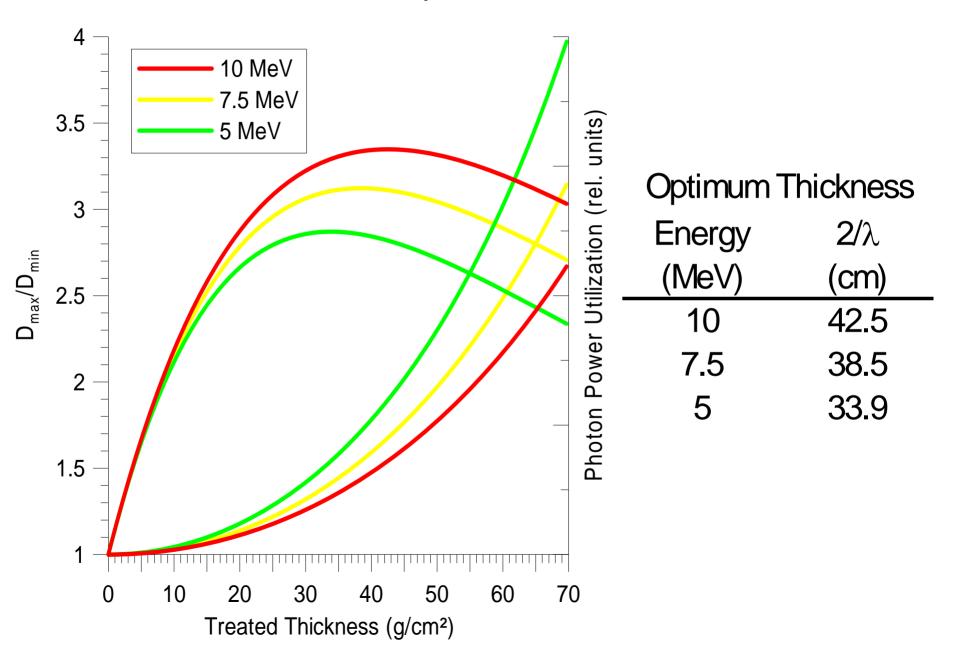
X-Ray Photon Angular Distribution



Broad Beam X-Ray Penetration in Water



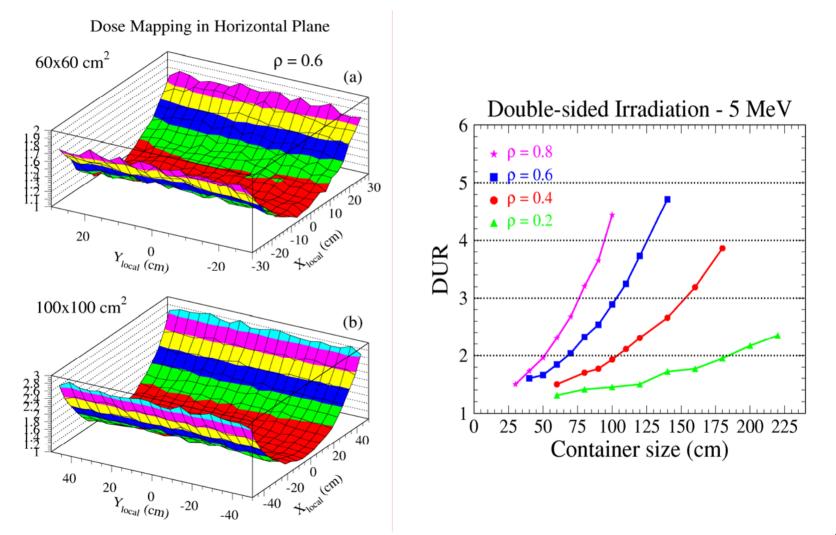
Two-Sided X-Ray Process in Water



Two-Sided X-Rays vs Gamma Rays

Electron Energy	X-Ray Efficiency	Tenth Value Layer Calculation	Optimum Thickness Double Sided	
(MeV)	(%)	(cm water)	(cm)	Max/Min
10.0	16.2	49.0	43	1.54
7.5	13.3	44.3	38	1.54
5.0	8.2	39.0	34	1.54
Co-60		31.0	28	1.75

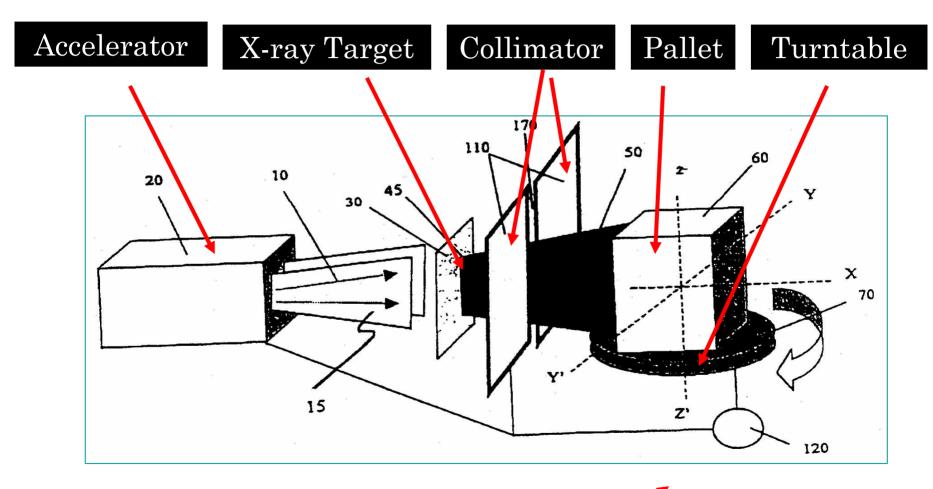
Two-Sided X-Ray Irradiation



Sterigenics Dual-Beam X-ray Facility

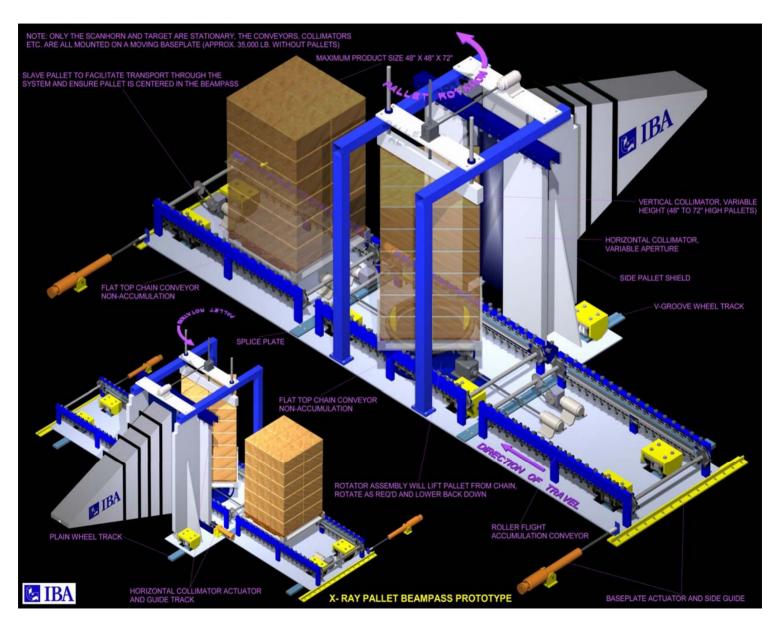


IBA PalletronTM Rotational Method





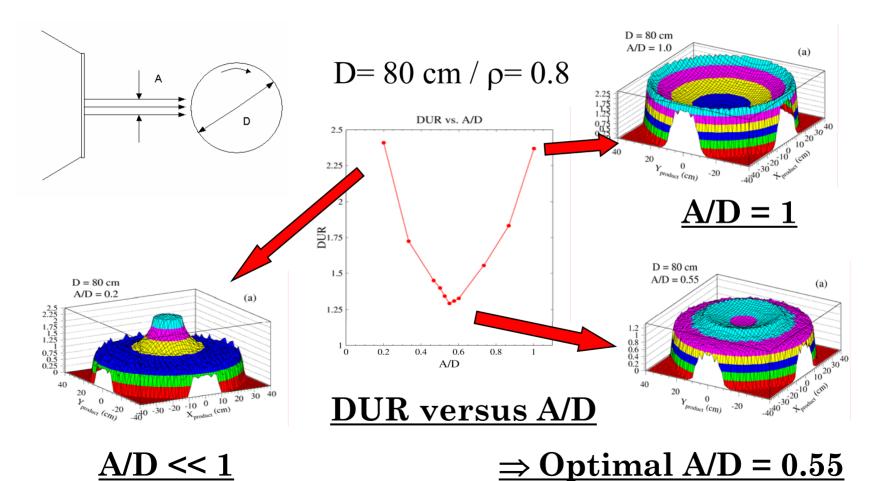
IBA PalletronTM Rotational Method



IBA Palletron[®] Dose Distribution Measurement Verification of Monte Carlo Simulation



IBA PalletronTM Rotational Method Cylinder Irradiation with X-Rays



IBA PalletronTM Performance Figures

r £ 0.4:

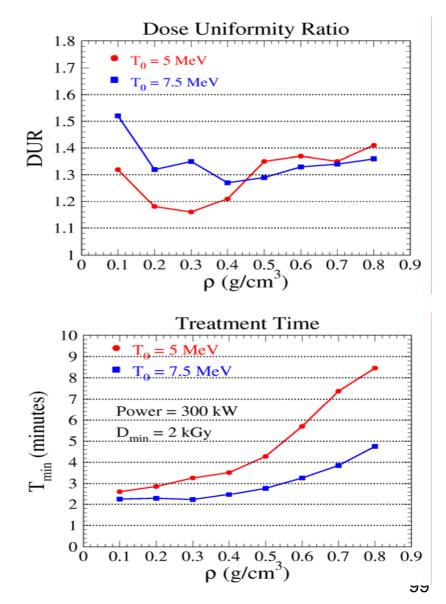
- constant rotation speed
- collimators widely open

r > 0.4:

- variable rotation speed
- aperture tuned to product density

Significant gain at 7.5 MeV:

- Better conversion efficiency
- More energetic X-Rays
- X-rays peaked forward



IBA PalletronTM Processing Capacities

Throughputs calculated with the following assumptions:

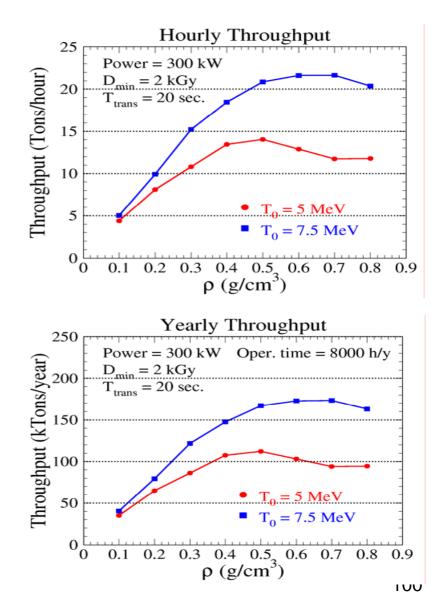
Beam = 5 MeV/300 kW or 7.5 MeV/300 kW

Minimal dose = 2 kGy

Transfer time between pallets = 20 seconds

Operating time = 8000 hours/year

110 kTons/year at 5 MeV for product density of 0.5 g/cm³



Direct Current Accelerators Single Gap – Extended Beam Multiple Gap – Scanned Beam

Microwave Linear Accelerators S-Band Systems L-Band Systems

Radio Frequency Accelerators Single Cavity – Single Pass Single Cavity – Multiple Pass

Direct Current Accelerators

Single Gap – Extended Beam

Electron Energy – 80 keV to 300 keV Electron Beam Power – up to 300 kW Electron Beam Width – up to 3 m

RPC BroadBeam® Electron Beam Processor



AEB Modular EB Emitter 120 keV - 40 mA



AEB Modular Two-Emitter Assembly

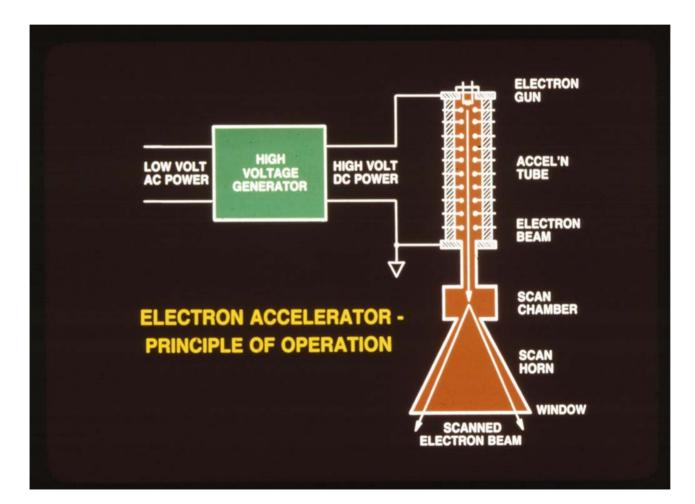


Direct Current Accelerators

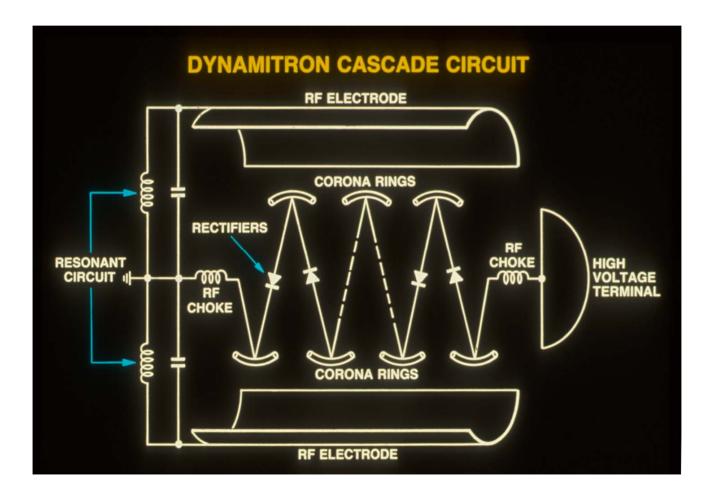
Multiple Gap – Scanned Beam

Electron Energy – 300 keV to 5 MeV Electron Beam Power – up to 300 kW Electron Beam Width – up to 3 m

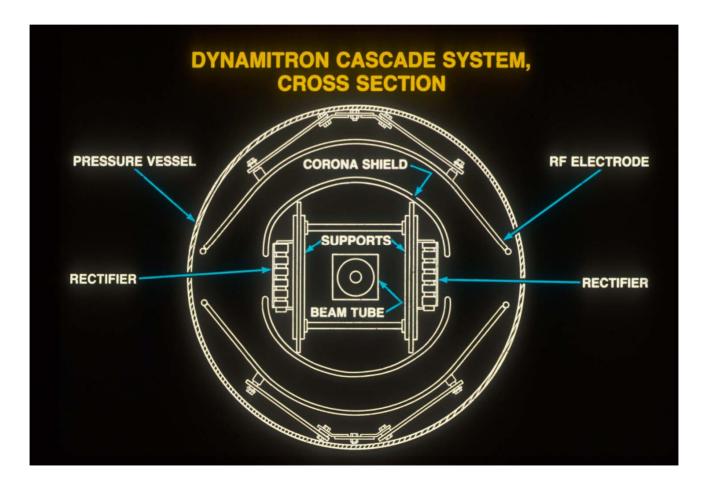
Multiple Gap – Scanned Beam DC Accelerator



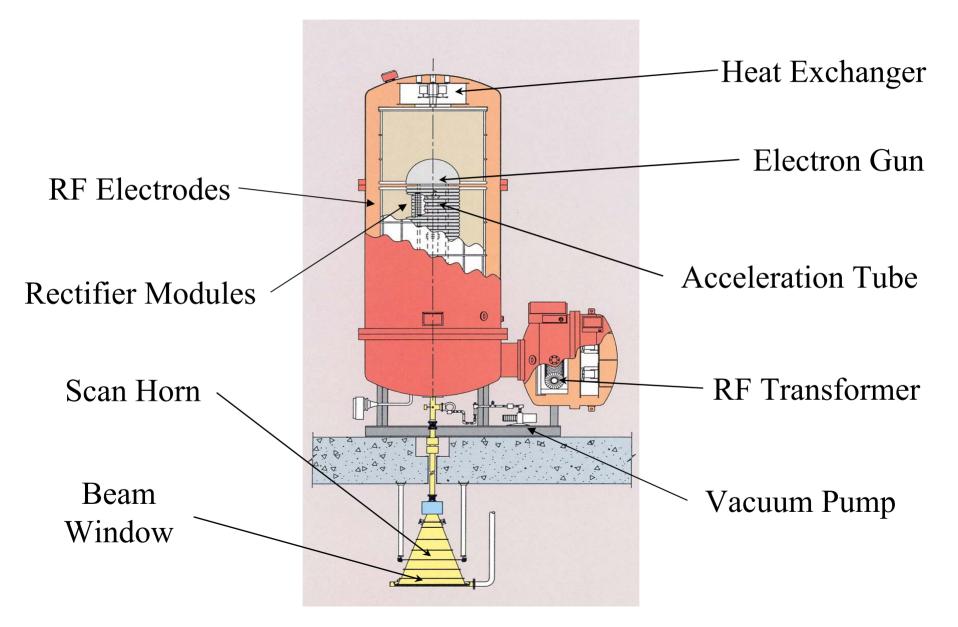
Parallel-Coupled Capacitive Cascade Circuit



Parallel-Coupled Capacitive Cascade Circuit



RDI Dynamitron[®] Assembly Drawing



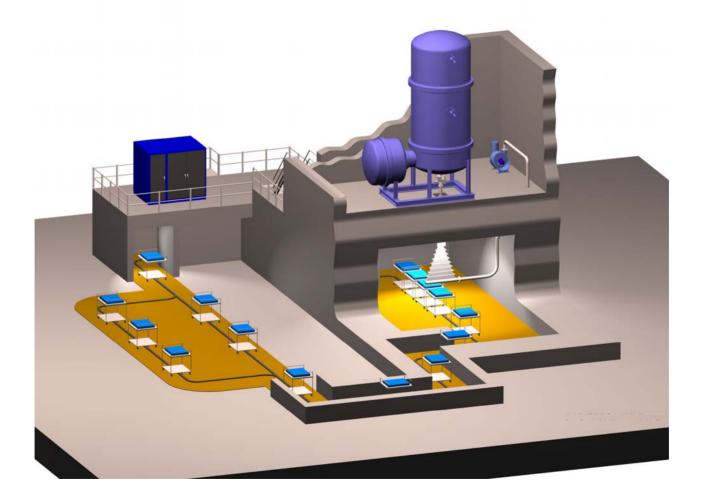
RDI Dynamitron[®] Assembly 5 MeV - 300 kW



RDI Dynamitron[®] Rectifier Column 5 MeV



RDI Dynamitron[®] EB Processing Facility

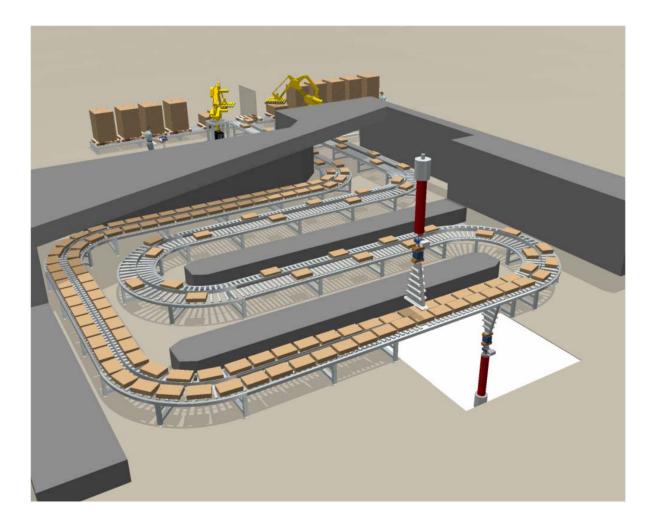


Microwave Linear Accelerators

S-Band Systems

Microwave Frequency – 3 GHz Electron Energy – 2 MeV to 20 MeV Electron Beam Power – up to 20 kW Electron Beam Width – up to 1 m

SureBeam Dual S-Band Linac EB Facility

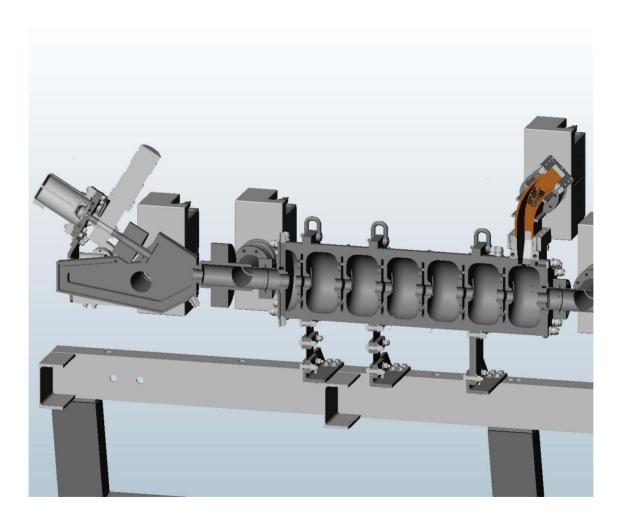


Microwave Linear Accelerators

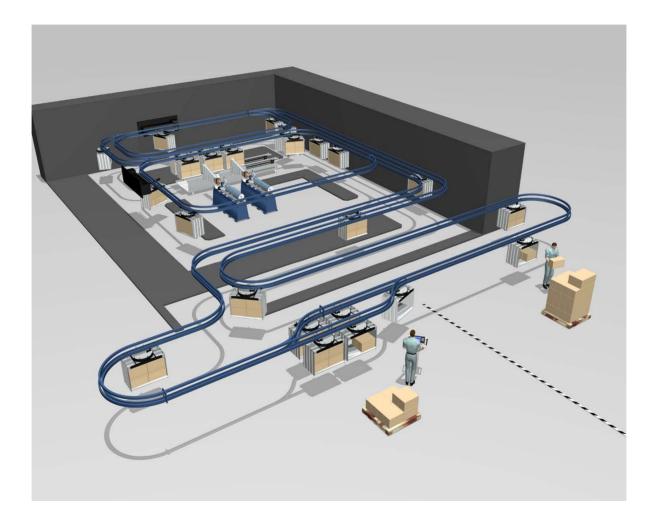
L-Band Systems

Microwave Frequency – 1.3 GHz Electron Energy – 5 MeV to 10 MeV Electron Beam Power – up to 80 kW Electron Beam Width – up to 1.5 m

SureBeam L-Band Linac 5 MeV - 80 kW



SureBeam Dual L-Band Linac X-Ray Facility



AECL Impela[®] L-Band Linac 10 MeV - 60 kW



Iotron Impela[®] L-Band Linac EB Facility



Radio Frequency Accelerators

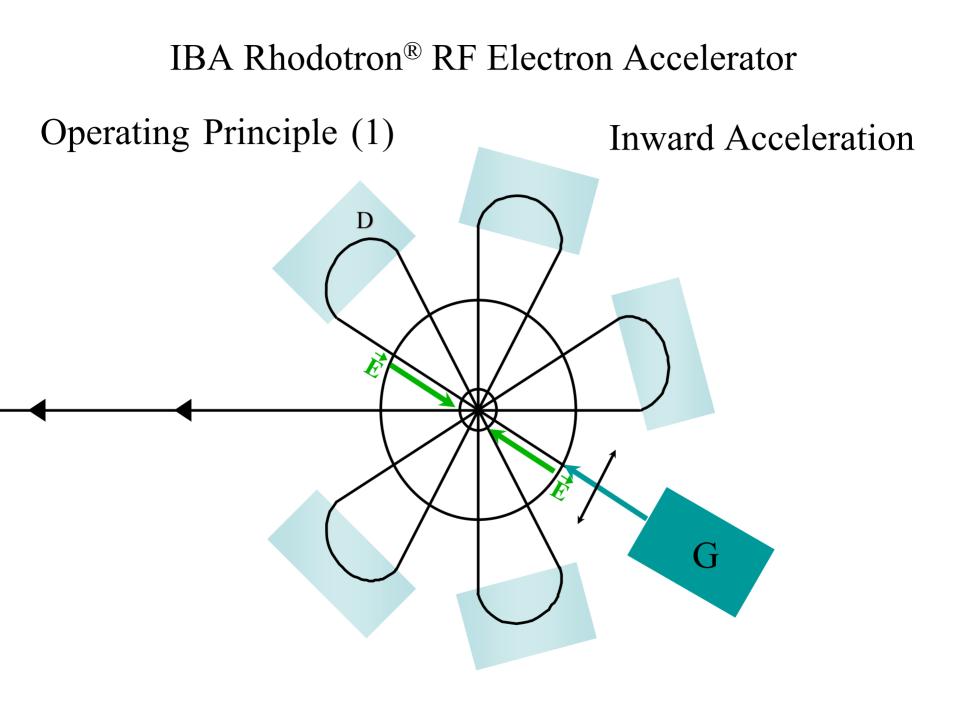
Single Cavity – Single Pass Systems

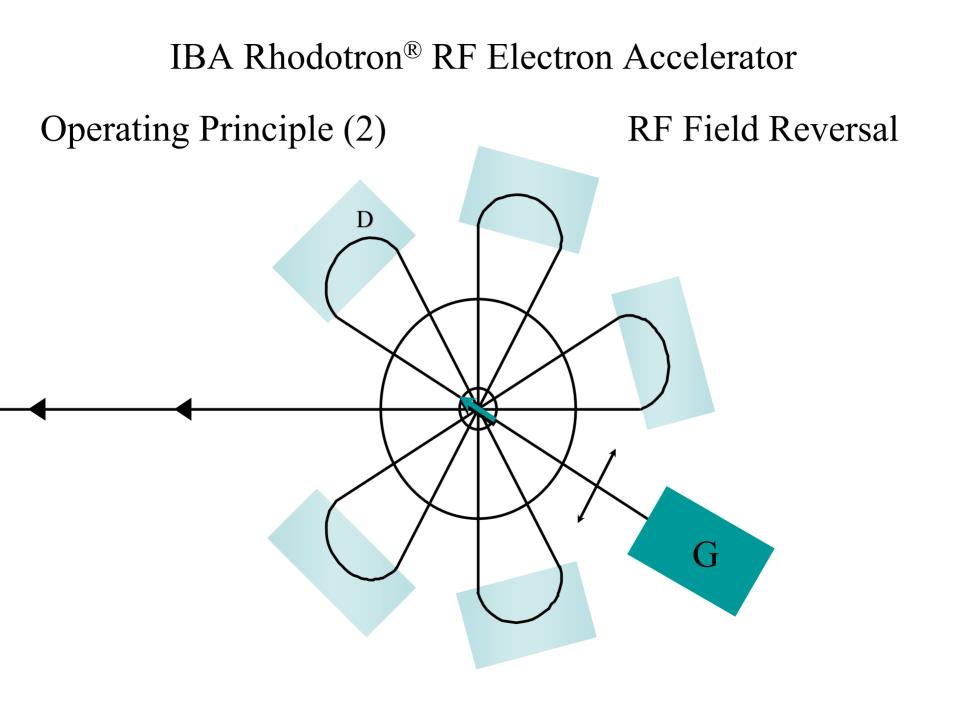
Radio Frequency – 100 to 200 MHz Electron Energy – 0.5 MeV to 4 MeV Electron Beam Power – up to 50 kW Electron Beam Width – up to 1 m

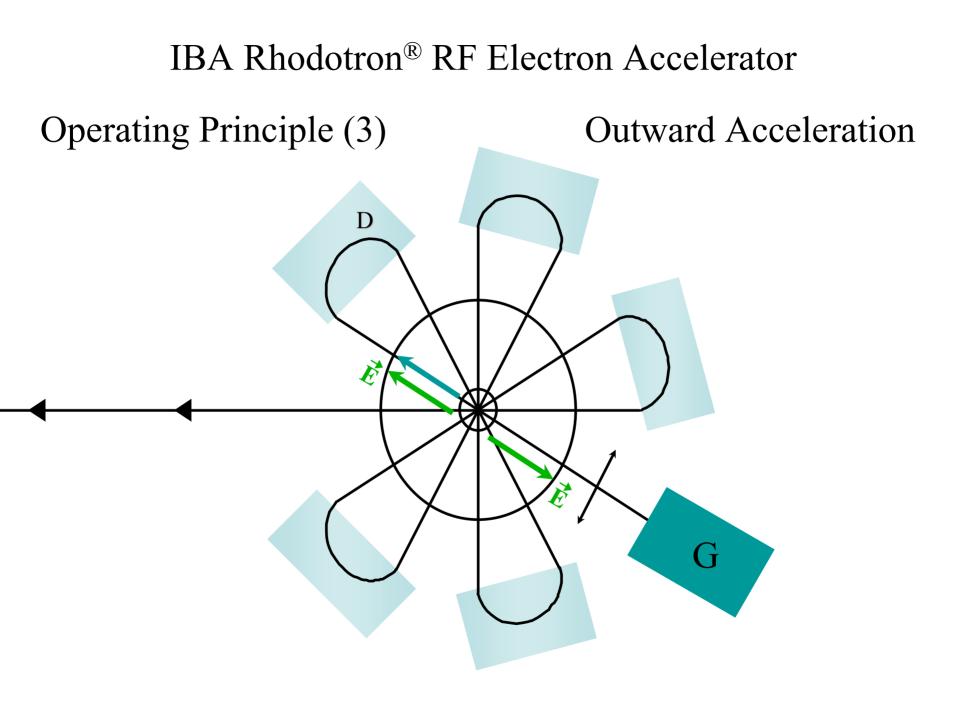
Radio Frequency Accelerators

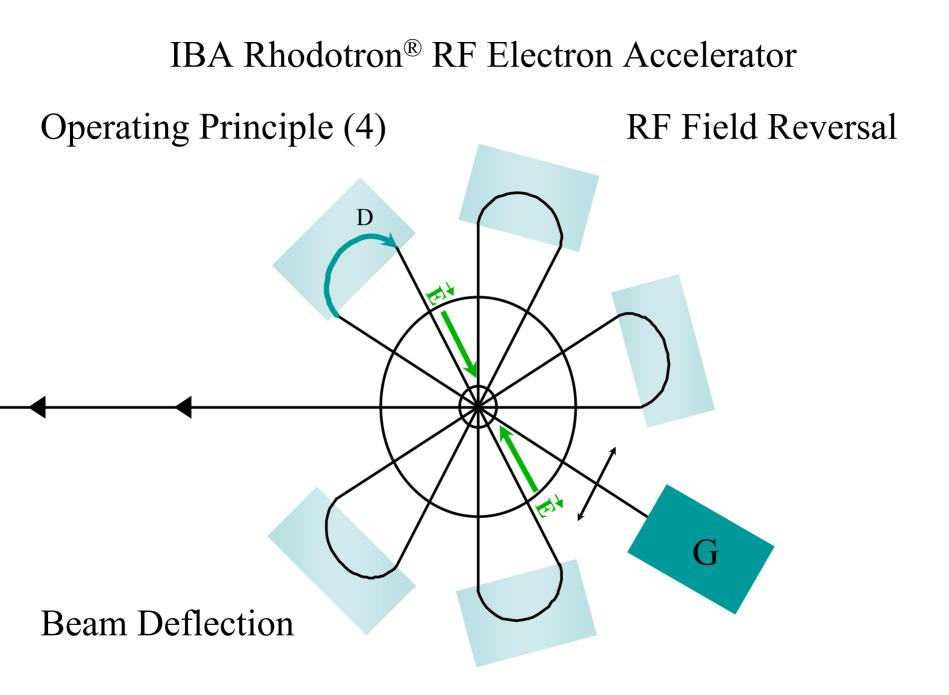
Single Cavity – Multiple Pass Systems

Radio Frequency – 107 to 215 MHz Electron Energy – 5 MeV to 10 MeV Electron Beam Power – up to 700 kW Electron Beam Width – up to 2 m



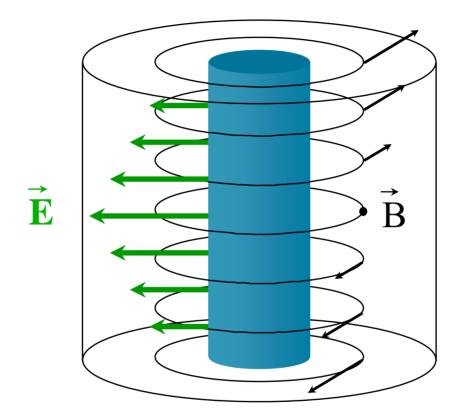






IBA Rhodotron[®] RF Electron Accelerator Operating Principle (5) D **T** External Beam Transport

IBA Rhodotron[®] RF Electron Accelerator



Electric (\vec{E}) and magnetic (\vec{B}) fields in a Rhodotron coaxial cavity

IBA Rhodotron® RF Electron Accelerator Copper Plated Steel Cavity



IBA Rhodotron® RF Electron Accelerator Assembly of Beam Reversing Magnets



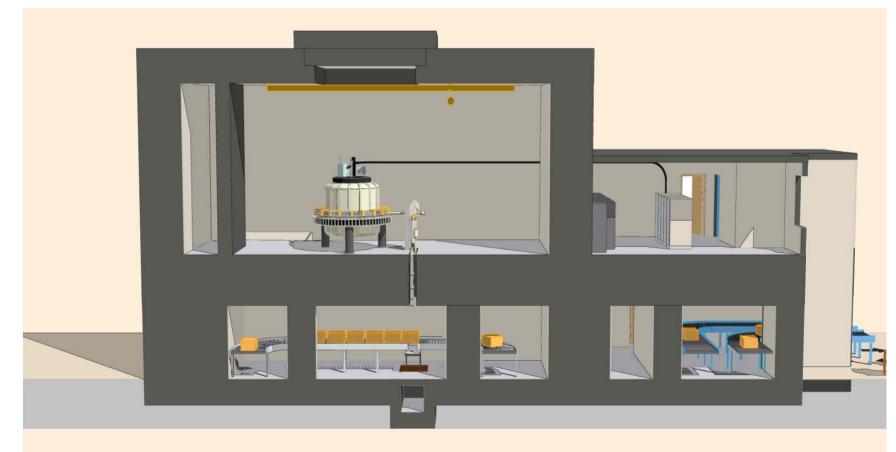
IBA Rhodotron® RF Electron Accelerator Model TT1000 7 MeV – 100 mA – 700 kW



IBA Rhodotron[®] Specifications

	<u>TT100</u>	TT200	TT300	TT1000
Energy (MeV)	3-10	3-1	3-10	5 – 7.5
Power range at 10 MeV (kW)	1-3	1-8	1-150	NA
at 5 MeV (kW)	1-18	1-80	1-135	1 - 500
at 7 MeV (kW)	1-25	1-80	1-150	1 - 700
Design Value (kW)	45	100	> 200	> 800
Full (cavity) diameter (m)	1.60 (1.05) 3.00 (2.00)	3.00 (2.00)	3.00 (2.00)
Full (cavity) height (m)	1.75 (0.75) 2.40 (1.80)	2.40 (1.80)	3.40 (1.80)
Weight (T)	2.5	11	11	11
MeV/pass	0.83	1.0	1.0	0.83 – 1.5
Number of passes	12	10	10	6
Stand-by kW used	< 15	< 15	< 15	<25
Full beam kW used	< 21	< 260	< 370 <10	00 @500 kW
			<14	00 @750 kW

IBA Rhodotron EB Processing Facility



Industrial Applications of Electron Accelerators

Conclusion

Ideas about how to accelerate atomic particles to high energies originated about 75 years ago. The motivation then was to investigate the structure of atomic nuclei.

Those early concepts have evolved into very complex accelerator technologies, which have many practical applications outside the field of nuclear physics.

Industrial Applications of Electron Accelerators

Conclusion

Radiation processing of materials and commercial products is one of those offshoots. It is a diverse field that has justified constructing over 1000 industrial electron beam irradiation facilities.

Some of the emerging applications, such as food irradiation and reduction of environmental pollution, offer the prospects of significant benefits to human health and wellfare.